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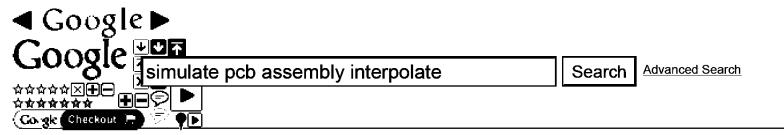
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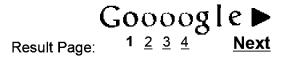
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... It is to this end that META (Mcro£lectronic Hhermal Analyser), the simulation routine presented
in ... across the PCB using this ap- proximation, it was shown that the PCB thermal resistance ... of
the delay function on the type of convective heat transfer, an interpolation between the ...
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S Goumas, GA Rovithakis, M ... - Image Processing. ..., 2002 - www-video.eecs.berkeley.edu
... Surface Mount technology Devices (SMDs) are in this direction, thus explaining the substantial increase ... placement, so no extra time and components are spent on an already faulty PCB. ... For designing and training the classifiers we employ the Monte Carlo simulation process, in ...
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W Zhiping, N Jingxu - ACTA MECHANICA SINICA (English Series), 2002 - cstam.org.cn ... PCB PCB BT BT ... It was found that the results from the numerical simulation are in good agreement with the results from the MDS tests, either by the type of failure site or fatigue life. ... Solder joint reliability of fine pitch surface mount technology assemblies. ... Cited by 6 - Related articles - View as HTML - All 2 versions

A profile identification system for surface **mount** printed circuit board **assembly**

YY Su, K Srihari, CR Emerson - Computers & industrial engineering, 1997 - Elsevier ... temperature, and the maximum temperature increase and decrease that the **PCB** and or ... The IR radiation forced convection oven temperature profile **simulation** generated by the ... Lea, C., (1988), A Scientific Guide To Surface **Mount** Technology, Electrochemical Publications, Ayr ... Cited by 9 - Related articles - BL Direct - All 8 versions

Critical factors affecting paste flow during the stencil **printing** of **solder** paste

R Durairaj, TA Nguty, NN Ekere - **Soldering** and Surface **Mount** ..., 2001 - emeraldinsight.com ... stencil walls compete directly with the adhesives/pull force on the **PCB** pads, often ... EK (1994), "Mapping of manufacturing process modelling", **Soldering** and Surface **Mount** Technology Journal ... Mannan, SH, Ekere, NN, Ismail, I., Currie, MA (1994), "Computer **simulation** of **solder** ... Cited by 11 - Related articles - BL Direct - All 6 versions

... of **solder** paste rheology with computational simulations of the stencil **printing** ...

R Durairaj, GJ Jackson, NN Ekere, G ... - **Soldering** and Surface ..., 2002 - emeraldinsight.com ... by computational **simulation**.This paper describes paste characterisation and computational **simulation** studies that ... is a critical stage in the mass production **assembly** of surface **mount** components. ... As **PCB** pad and component lead sizes continue to reduce, most paste suppliers ... Cited by 12 - Related articles - BL Direct - All 5 versions

... -based process planning system for the surface mount manufacture of PCBs

K Srihari, JA Cecil, CR Emerson - The International Journal of Advanced ..., 1994 - Springer ... The outputs that are then formatted and provided to the user include: 1. The suggested sequence of surface **mount assembly** oper- ations for a **PCB**. Page 6. ... The **simulation** would help to visualise the movement of the **PCBs**, the working of the **assembly** line, etc. ... Cited by 7 - Related articles - BL Direct - All 3 versions

Flow processes in solder paste during stencil printing for SMT assembly

SH Mannan, NN Ekere, I Ismail, MA Currie - Journal of Materials Science: ..., 1995 - Springer ... 1. Introduction The use of surface **mount** technology (SMT) has grown rapidly in recent years, but ... After the paste has entered the apertures, the next crucial stage is stencil-**PCB** separation. ... It has been observed in a computer **simulation** [14] that a wider particle size distribution ... Cited by 8 - Related articles - BL Direct

Effect of gold on the reliability of fine pitch surface mount solder joints

J Glazer, PA Kramer, JW Morris Jr - Circuit World, 1992 - emeraldinsight.com ... of the rods does not appear random; for example, near the **solder-PCB** interface the ... However, in joints that were subjected to the adjacent rework **simulation** treatment of 170°C ... D., Kral, J. and Wells, B., 'Experimental and Statistical Analyses of Surface-mount Technology PLCC ... Cited by 15 - Related articles - All 5 versions

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D Santos, J Kane, F Caballero, K Nagarajan - Computers & Industrial ..., 1995 - Elsevier ... the numbers and types of the various passive and active surface **mounted** components on ... systems to its customers follows the flow in Figure 1. Line **Simulation** Inputs Spreadsheet ... I Cost Related Inputs Economic Analysis Figure 1. Components in **PCB Assembly** Line Proposal ... Cited by 3 - Related articles - BL Direct - All 3 versions

[CITATION] Interconnect Design and Reliability of Land Grid Array CSPs ZP Wang, DJ Xie, KM Chua - Proceeding of Chip Scale Packaging Symposium, ..., 1999 Cited by 1 - Related articles

Planning for printed circuit board assembly: the state-of-the-art review

P Ji, YF Wan - International Journal of Computer Applications in ..., 2001 - Inderscience ... In this method, component leads are **soldered** on the surface of the board, rather than ... 20 Feldmann, K., Franke, J. and Rothhaupt, A. (1994) 'Optimization and **simulation** of the ... K. (1993) 'A solution methodol- ogy for the multiple batch surface **mount PCB** placement sequence ... Cited by 15 - Related articles - BL Direct - All 8 versions

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Neural network solder paste inspection system

SM Bryant, KH Loewenthal - US Patent 5,751,910, 1998 - Google Patents ... USING CRISP INPUT VECTOR APPLY BACK PROPAGATION TRAINING USING **FUZZY** OUTPUT VECTOR HAS ... Neural networks have also been used in imaging **mount** technology (SMT) components or ... paradigm, cally secured and electrically connected to the **PCB** by Neural ... Cited by 10 - Related articles - All 4 versions

[BOOK] Spatial reasoning for effective GIS

JK Berry - 1996 - books.google.com

... E-mail: books@gisworld.com Edited by John Hughes Designed and composed by Wade Smith Project managed by Bea Ferrigno Second **Printing**. ... For example, a geographic distribution (3-D surface) of **PCB** concentra- tions in an aquifer can be **interpolated** from water ... Cited by 50 - Related articles - All 5 versions

[PDF] •System implementation, modeling and defects pattern recognition for flip chip ...

S Liu - 2001 - me.gatech.edu

... It can also be extended to inspect solder bumps on BGAs, chip scales, MCMs, and other surface mount components in the future. ... The screen-printing process puts pastes of solders on ... After assembling the entire printed circuit board (PCB), the testing fixture checks for Page 26. ... Related articles - View as HTML - All 5 versions

[BOOK] Computational intelligence in manufacturing handbook

J Wang, A Kusiak - 2001 - books.google.com

... It represents a union of neural networks, **fuzzy** systems, evolutionary computation techniques, and other emerging intelligent agents and technologies. ... Chapter 5 by Kazerooni et al. discusses an application of **fuzzy** logic to design flexible manufacturing systems. ...

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Devices and methods for optically identifying characteristics of material objects

I Wunderman, AE Smith, VK Lumba - US Patent 6,122,042, 2000 - Google Patents ... object surface. FIG. 2A is a cross-sectional view of a particular embodi- ment of an IDEA probe. FIG. 2B details the drive electronics of an LED **PCB**. FIG. 2C details the detector electronics 42 of a detector **PCB**. FIG. 2D shows ...

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[ΒΟΟΚ] Junk science judo: Self-defense against health scares & scams

SJ Milloy - 2001 - books.google.com

... All right reserved. Second **printing**: March 2002 Library of Congress Cataloging-in-Publication Data Milloy, Steven J. Junk science judo: self-defense against health scares and scams / by Steven J. Milloy. ... Broadcast media care about ratings. **Print** media care about circu- lation. ... Cited by 15 - Related articles

A review of computer graphics publications

ID Benest - Computers & Graphics, 1979 - Elsevier

... graphics in computer circuit analysis 13.3 Printed circuit board layout at REDAC Software Limited 13.4 Surface plotter 13.5 PLOT 3D surface plotter 13.6 Surface interpolation 13.7 Polygon ... The image so produced was used for **printing** by the standard photo- offset technique. ... Cited by 5

•A data structure and query algorithm for a database of areal entities

DJ Abel, JL Smith - Australian Computer Journal, 1984 - acs.org.au

... The scheduling technique has provision for putting such jobs 'to one side' and for informing the operators of tape **mounting** requirements, without holding up the ... Keywords = {Photocomposition, **Printing** Industry, Text Composition ... Title = {A Stable Method of Inverse Interpolation},. ... Cited by 27 - Related articles - View as HTML - All 2 versions

[BOOK] Deep Descent: Adventure and Death Diving the Andrea Doria

KF McMurray - 2002 - books.google.com

... display. The Andrea Doria is often called the "Mount Everest of wreck div- ing," although there are deeper and more challenging wrecks for divers to explore. Yet the Andrea Doria has a mystique about her: her XI I Page 14. Foreword ... Related articles

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Simulation software for surface mount assembly

TM Tirpak - ... of the 25th conference on Winter simulation, 1993 - portal.acm.org ... of the software, ie, the routines for managing input data, outputs, and process models. ... industry and typi- cally involves the following process steps: screen printing (solder paste), glue ... These include the sequence of component placements on a printed circuit board, the allocation ... Cited by 16 - Related articles - BL Direct - All 3 versions

... of solder paste rheology with computational simulations of the stencil printing ...

R Durairai, GJ Jackson, NN Ekere, G ... - Soldering and Surface 2002 - emeraldinsight.com ... paste flows through the apertures, which are aligned precisely with the printed circuit board (PCB ... non-Newtonian constitutive model for viscosity/shear rate given by the Cross model above. ... be argued that the lower pressure generated by the conventional lead solder paste (P1 ... Cited by 12 - Related articles - BL Direct - All 5 versions

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P Ji, YF Wan - International Journal of Computer Applications in ..., 2001 - Inderscience ... In this method, component leads are soldered on the surface of the board, rather than being inserted into ... A mathematical model was formulated as a cardinality set-covering problem ... Drezner and Nof [16] described a robotic cell for printed circuit card assembly and identi Ūed the ... Cited by 15 - Related articles - BL Direct - All 8 versions

[PDF] •Failure-assessment software for circuit-card assemblies

M Osterman, TJ Stadterman - PROCEEDINGS OF THE ANNUAL ..., 1999 - calce.umd.edu ... Stakeholders Process Soldering, laminating, plating, etching Failure Models Wearout, overstress Test Laboratories eg, Bell Technologies, Lucent Technologies Inputs ... Performance Analysis Cross-talk, time delay, failed circuit identification, EM compatibility, radiation resistance ... Cited by 15 - Related articles - View as HTML - BL Direct - All 3 versions

... mount technology electronic assembly plant: An integrated model using simulation

S Lambert, G Abdulnour, J Drolet, B Cyr - International Journal of Flexible ..., 2005 - Springer ... The demand for automated printed circuit board assembly continues to increase with the miniaturization ... to improve flexibility and productivity of the SMT line an integrated model using simulation ... The company's production system, an SMT line, consisted of a solder paste printer ... Cited by 4 - Related articles - BL Direct - All 2 versions

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Using computer **models** to identify optimal conditions for flip-chip **assembly** and ...

C Bailey, H Lu, G Glinski, D Wheeler, P Hamilton, M ... - Circuit World, 2001 - emeraldinsight.com ... Greg Glinski, Daniel Wheeler, Phil Hamilton, Mike Hendriksen and Brian Smith Using computer models to identify optimal conditions for flip-chip assembly and reliability Circuit World 28 ... solder paste The purpose of the stencil printing process is to deposit solder paste at ... Cited by 5 - Related articles - BL Direct - All 4 versions

... profile control of the second-side reflow process in surface mount assembly

TN Tsai, T Yang - Journal of Manufacturing Technology ..., 2005 - emeraldinsight.com ... The efficiency and effectiveness of the proposed BPN model can facilitate the reflow oven setup procedure – a procedure that is often time-consuming if undertaken by a trial-and-error approach. ... Manko, HH (1995), Soldering Handbook for Printed Circuits and Surface ... Cited by 3 - Related articles - All 5 versions

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SCK Shiu, ECC Tsang, MB Lam, DS Yeung - ... CONFERENCE ON SYSTEMS ..., 1998 - Citeseer ... The constructed model adopted in this paper was based on a factory's Surface Mount Technology process of Printed Circuit Board Assembly ... printer process, transportation operation, components pick and place process, error detection and recovery process, solder paste re ... Cited by 2 - Related articles - View as HTML - BL Direct - All 5 versions

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D Santos, J Kane, F Caballero, K Nagarajan - Computers & Industrial ..., 1995 - Elsevier ... While different types of boards may require different amounts of time in the solder paste application ... At this point, the simulation model is completed when inputs are added. ... number of components per circuit, number of circuits per board, materials cost per circuit, etc.) the program ... Cited by 3 - Related articles - BL Direct - All 3 versions

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